ABSTRACT

INTEGRATED CIRCUIT LEADFRAME AND

FABRICATION METHOD THEREFOR

An integrated circuit leadframe and a fabrication method for fabricating the integrated circuit leadframe include forming a leadframe having leads around a die pad that has a peripheral die pad rim. A discrete, alternately staggered surface configuration is formed in the die pad rim. The discrete, alternately staggered surface configuration creates space in the die pad for connecting and separating ground bond wire-bonds and down bond wire-bonds, and provides for locking encapsulant firmly to the die pad. (Figure 1)